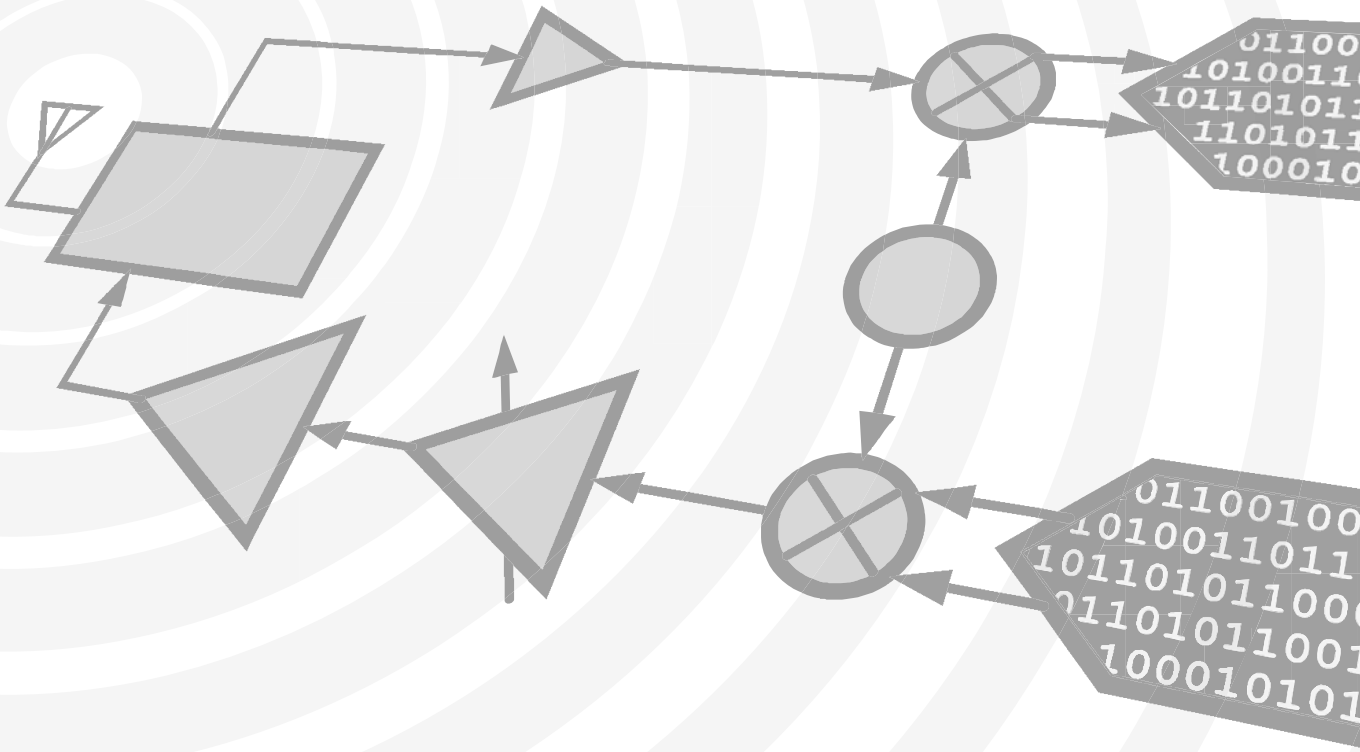
ANALOG DEVICES

Hittite MICROWAVE PRODUCTS FROM ANALOG DEVICES

Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED



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Hittite MICROWAVE CORPORATION

20 Alpha Rd
Chelmsford MA 01824
Tel:{978} 250-3343
Fax: {978} 250-3373

LP6 E SiGe

Product Environmental Data Sheet

Product Information					
Date/Time Revision:	February 25, 2005				
Manufacture site:	Chelmsford MA				
Product Number	Generic: LP6, Plastic Encapsulated Microcircuit				
Product Name	Surface Mount SiGe Semiconductor				
Product Mass	Grams:	Min 0.088074	Max 0.107646	Nominal 0.09786	
Product Note					

Material Composition Information

Component	Mateial Part Name	Material	Material Trade Name	Material Mass (g) *Minimum*	Material Mass (g) *Maximum*	Percent of product (%) *Minimum*	Percent of product (%) *Maximum*
A	Lead Frame	Metal	Copper Lead Frame	0.0352	0.0484	40.0%	45.0%
B	Mold Compound	Polymer	Sumitomo G770	0.0405	0.0538	46.0%	50.0%
C	Epoxy, Die attach	Epoxy	Sumitomo CRM1076DJ	0.0009	0.0022	1.0%	2.0%
D	Semiconductor, SiGe	Non- metal, Non- polymer	Silicon/Germanium	0.0009	0.0022	1.0%	2.0%
E	Bond Wire, Gold	Metal	Wire	0.0004	0.0011	0.5%	1.0%
F	Lead Finish	Sn	Plating Coat	0.0009	0.0022	1.0%	2.0%
Substance	**Substance Name**	**Substance CAS#**	**Substance Note**	**Substance Mass (g) *Minimum***	**Substance Mass (g) *Maximum***	**Percent of Substance (%) *Minimum***	**Percent of Substance (%) *Maximum***
A	**Copper Lead Frame**						
A1	Cu	7440-50-8	n/a	0.034173	0.047472	97.00%	98.00%
A2	Fe	7439-89-6	n/a	0.000932	0.001292	2.30%	2.40%
A3	Zn	7440-66-6	n/a	0.000001	0.000003	0.11%	0.13%
A4	P	7723-14-0	n/a	0.000000	0.000001	0.02%	0.04%
B	**Mold Compound**						
B1	Silica Fused	60676-86-0	n/a	0.030386	0.051132	75.00%	95.00%
B2	Epoxy Resin A	(Trade Secret)	n/a	0.000405	0.002691	1.00%	5.00%
B3	Epoxy Resin B	(Trade Secret)	n/a	0.000405	0.002691	1.00%	5.00%
B4	Phenol Resin A	(Trade Secret)	n/a	0.000405	0.002691	1.00%	5.00%
B5	Phenol Resin B	(Trade Secret)	n/a	0.000405	0.002691	1.00%	5.00%
B6	Metal Hydroxide	(Trade Secret)	n/a	0.000203	0.001346	0.50%	2.50%
B7	Carbon Black	1333-86-4	n/a	0.000041	0.000269	0.10%	0.50%
C	**Die Attach Epoxy**						
C1	Silver	7440-22-4	n/a	0.000572	0.001830	65.00%	85.00%
C2	Epoxy Resin	9003-36-5	n/a	0.000132	0.000538	15.00%	25.00%
C3	t-Butyl phenyl glycidyl ether	3101-60-8	n/a	0.000044	0.000215	5.00%	10.00%
C4	Phenolic hardener	92-88-6	n/a	0.000009	0.000043	1.00%	2.00%
C5	Butyl cellosolve acetate	112-07-2	n/a	0.000004	0.000032	0.50%	1.50%
D	**SiGe Semiconductor**						
D1	Si	7440-21-3	n/a	0.000661	0.001830	75.00%	85.00%
D2	Ge	7440-56-4	n/a	0.000132	0.000538	15.00%	25.00%
E	**Bond Wire**						
E1	Gold (Au)	7440-57-5	Die Attach, wirebond	0.000440	0.001076	99.99%	100.00%
F	**Solder**						
F1	Tin	7440-31-5	Tin, Lead solder	0.000881	0.002153	99.99%	100.00%

NOTE: *CAS in not available for proprietary substances.All percentages are calculated from mass data declared. Material trade names are not applicable to some common materials for constant composition. When CAS is unavailable, vendor supplier comments such as PROPRIATARY or TRADE SECRET will be documented*

Flammability

The plastic mold compound used for this device has been tested for flammability of plastic materials used for parts in devices and appliances and is classified as UL-94 V0.

Absence of Hazardous Substances

Our material composition policy is to declare all substances intentionally added in our products and documented by our vendors. Additionally we confirm the following regulated substances known to be in electronics are not intentionally added or knowingly present in our semiconductor products or product packaging: Cadmium and cadmium compounds, mercury and mercury compounds, hexavalent chromium compounds, polychlorinated biphenyl (PCB), polychlorinated naphthalenes (PCN), polybrominated diphenyl ether (PBDE), decabromodiphenyl ether(DecaBDE), short chain paraffins (CP) (C10-13) (Cl = 50 wt% or more), mirex (perchlordecone), TBBP-A-bis, organic tin compounds (tributyl tin compounds / triphenyl tin compounds) Asbestos, formaldehyde and Azo compounds.

Product Life Cycle Information

Our devices are often incorporated into printed circuit boards and then assembled with other parts into electronic systems. In the U.S.A., end-of-life printed circuit boards {waste}, are considered scrap metal by the Environmental Protection Agency {EPA} when they are recycled {USEPA Mgt. memo, Regulatory Status or Printed Circuit Boards, Aug 26, 1992}. If any of our products are disposed of as part of a printed circuit board, the entire assembly is treated as scrap metal. Approved printed circuit recycling companies either have proper facilities or have access to secondary metal smelters and refiners which can safely recycle scrap electronic components or assemblies